

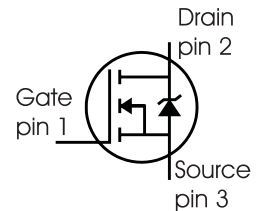
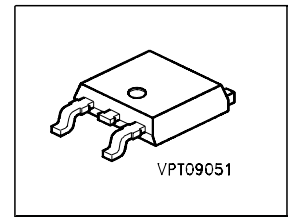
**OptiMOS Power-Transistor**  
Feature

- N-Channel
- Enhancement mode
- Logic Level
- 175°C operating temperature
- Avalanche rated
- dv/dt rated

**Product Summary**

$V_{DS}$	55	V
$R_{DS(on)}$	13	mΩ
$I_D$	30	A

P-TO252



Type	Package	Ordering Code	Marking
SPD30N06S2L-13	P-TO252	Q67040-S4254	2N06L13

**Maximum Ratings**, at  $T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25\text{ °C}$ , <sup>1)</sup> $T_C = 100\text{ °C}$	$I_D$	30 30	A
Pulsed drain current $T_C = 25\text{ °C}$	$I_{D\text{ puls}}$	120	
Avalanche energy, single pulse $I_D = 30\text{ A}$ , $V_{DD} = 25\text{ V}$ , $R_{GS} = 25\text{ Ω}$	$E_{AS}$	240	mJ
Reverse diode dv/dt $I_S = 30\text{ A}$ , $V_{DS} = 44\text{ V}$ , $di/dt = 200\text{ A/μs}$ , $T_{j\text{max}} = 175\text{ °C}$	dv/dt	6	kV/μs
Gate source voltage	$V_{GS}$	±20	V
Power dissipation $T_C = 25\text{ °C}$	$P_{\text{tot}}$	125	W
Operating and storage temperature	$T_j, T_{\text{stg}}$	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.2	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	100	
SMD version, device on PCB: @ min. footprint @ 6 cm <sup>2</sup> cooling area <sup>F)</sup>	$R_{thJA}$	-	-	75 50	

**Electrical Characteristics**, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain-source breakdown voltage $V_{GS}=0V, I_D=1mA$	$V_{(BR)DSS}$	55	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=80\mu A$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS}=55V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=55V, V_{GS}=0V, T_j=125^\circ C$	$I_{DSS}$	-	0.01 1	1 100	$\mu A$
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	$I_{GSS}$	-	1	100	nA
Drain-source on-state resistance $V_{GS}=4.5V, I_D=30A$	$R_{DS(on)}$	-	13.3	17	m $\Omega$
Drain-source on-state resistance $V_{GS}=10V, I_D=30A$	$R_{DS(on)}$	-	9.8	13	

<sup>1</sup>Current limited by bondwire; with a  $R_{thJC} = 1.2\text{ K/W}$  the chip is able to carry  $I_D = 63A$  and calculated with max. source pin temperature of  $85^\circ C$ .

<sup>2</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu m$  thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic Characteristics**

Transconductance	$g_{fs}$	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 30\text{A}$	27	53	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	-	1760	2200	pF
Output capacitance	$C_{oss}$		-	430	540	
Reverse transfer capacitance	$C_{rss}$		-	115	170	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 30\text{V}$ , $V_{GS} = 4.5\text{V}$ , $I_D = 30\text{A}$ , $R_G = 3.6\Omega$	-	7	11	ns
Rise time	$t_r$		-	14	21	
Turn-off delay time	$t_{d(off)}$		-	8	12	
Fall time	$t_f$		-	13	20	

**Gate Charge Characteristics**

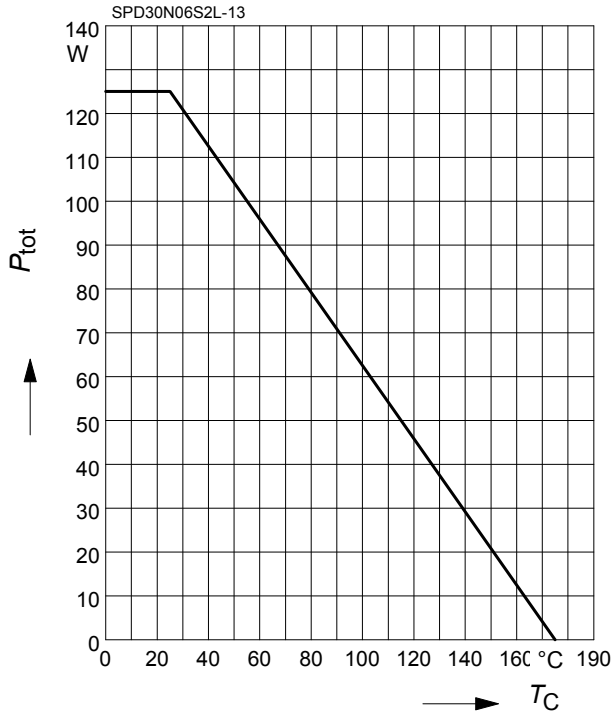
Gate to source charge	$Q_{gs}$	$V_{DD} = 44\text{V}$ , $I_D = 30\text{A}$	-	6	7.5	nC
Gate to drain charge	$Q_{gd}$		-	16	24	
Gate charge total	$Q_g$	$V_{DD} = 44\text{V}$ , $I_D = 30\text{A}$ , $V_{GS} = 0$ to $10\text{V}$	-	52	65	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 44\text{V}$ , $I_D = 30\text{A}$	-	3.4	-	V

**Reverse Diode**

Inverse diode continuous forward current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	-	-	30	A
Inverse diode direct current, pulsed	$I_{SM}$		-	-	120	
Inverse diode forward voltage	$V_{SD}$	$V_{GS} = 0\text{V}$ , $I_F = 30\text{A}$	-	0.9	1.3	V
Reverse recovery time	$t_{rr}$	$V_R = 30\text{V}$ , $I_F = I_S$ , $di_F/dt = 100\text{A}/\mu\text{s}$	-	33	41	ns
Reverse recovery charge	$Q_{rr}$		-	71	90	nC

### 1 Power dissipation

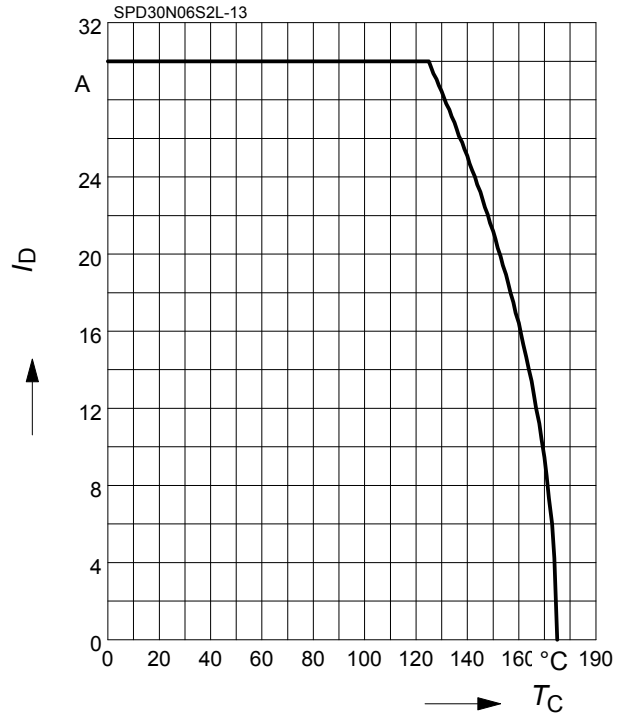
$$P_{tot} = f(T_C)$$



### 2 Drain current

$$I_D = f(T_C)$$

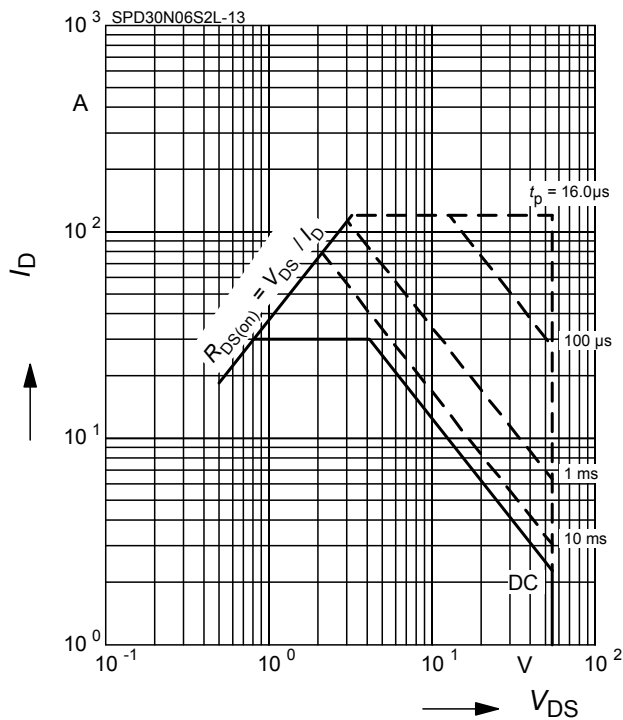
parameter:  $V_{GS} \geq 10\text{ V}$



### 3 Safe operating area

$$I_D = f(V_{DS})$$

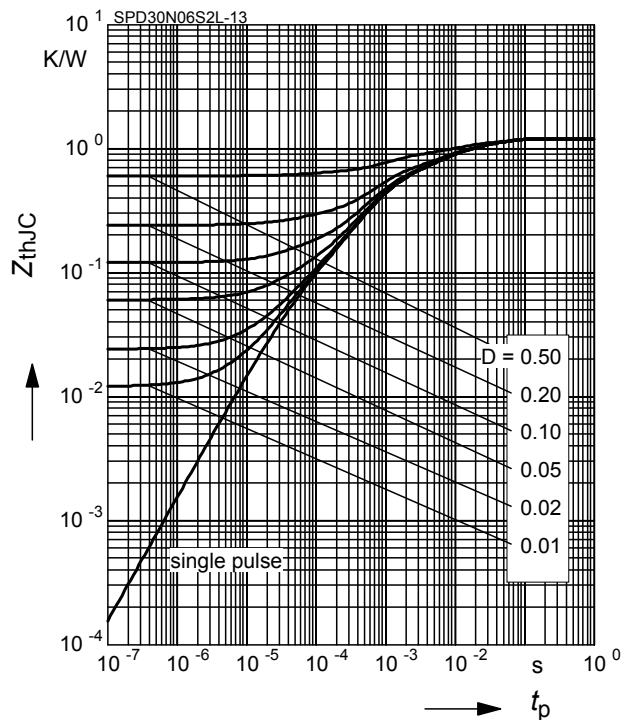
parameter:  $D = 0, T_C = 25\text{ °C}$



### 4 Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

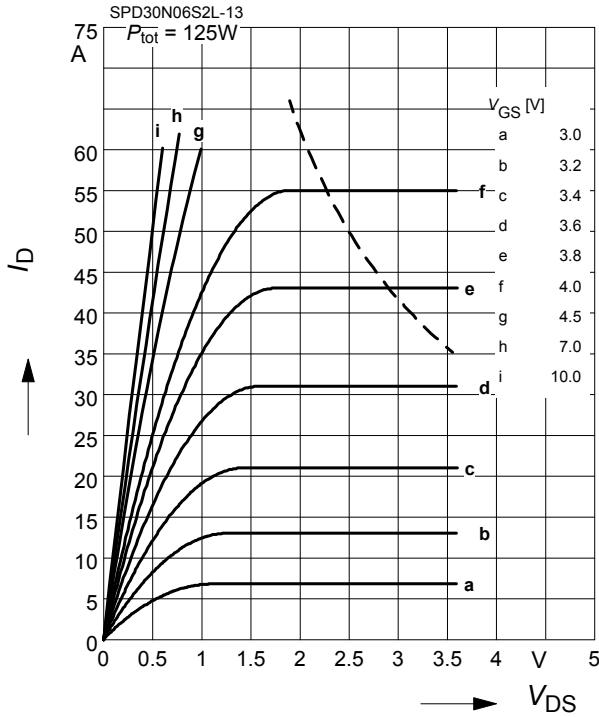
parameter:  $D = t_p/T$



**5 Typ. output characteristic**

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

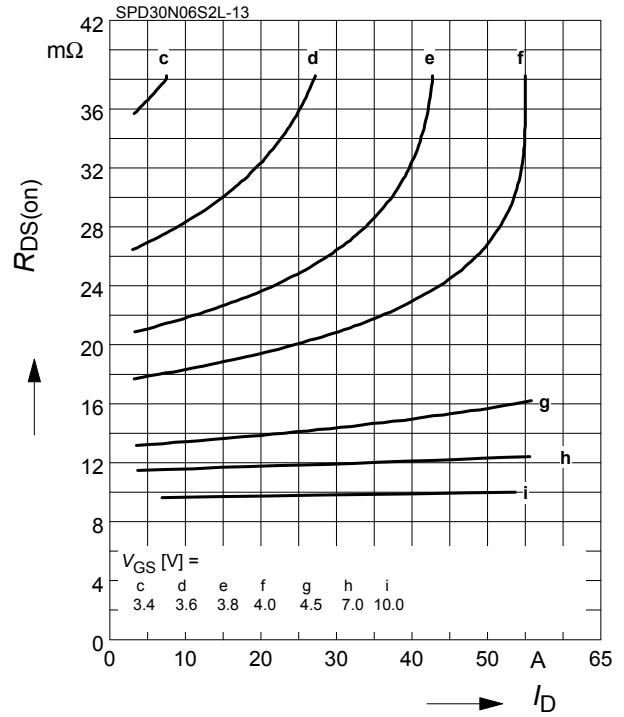
parameter:  $t_p = 80 \mu\text{s}$



**6 Typ. drain-source on resistance**

$R_{DS(on)} = f(I_D)$

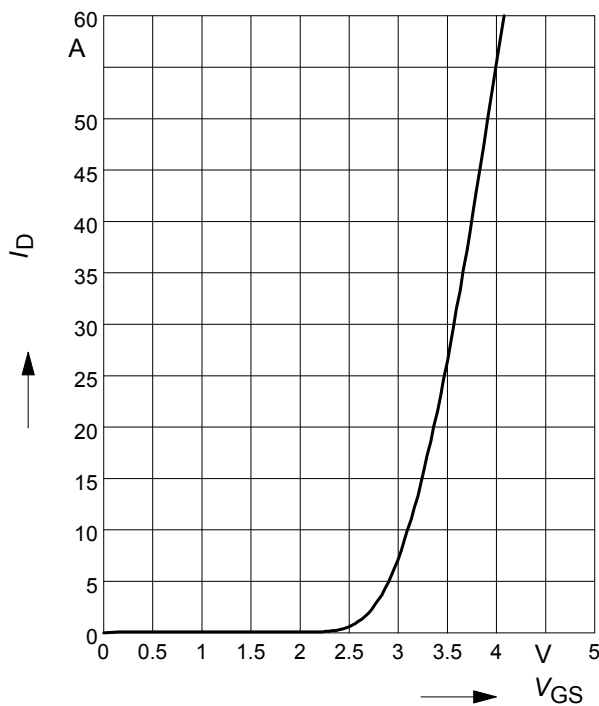
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

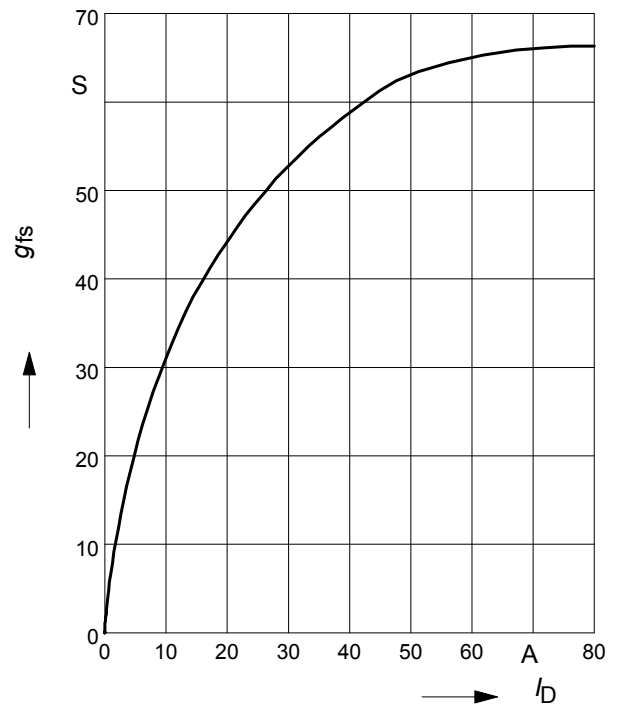
parameter:  $t_p = 80 \mu\text{s}$



**8 Typ. forward transconductance**

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

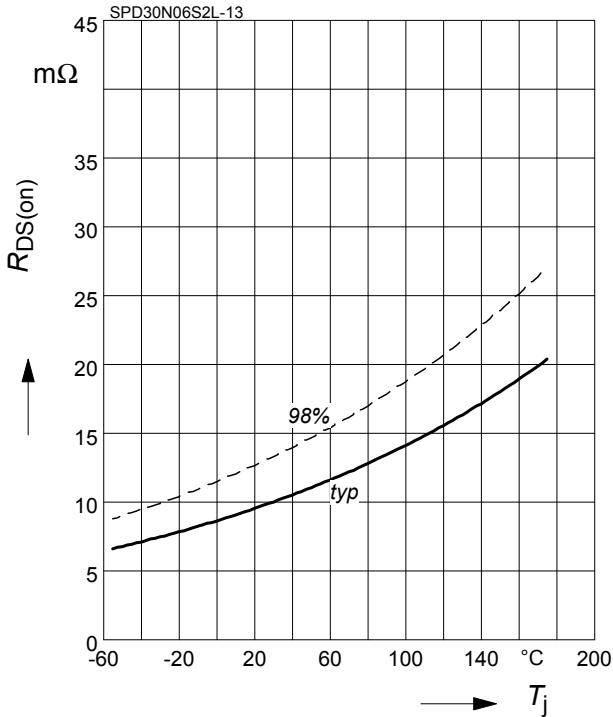
parameter:  $g_{fs}$



**9 Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j)$$

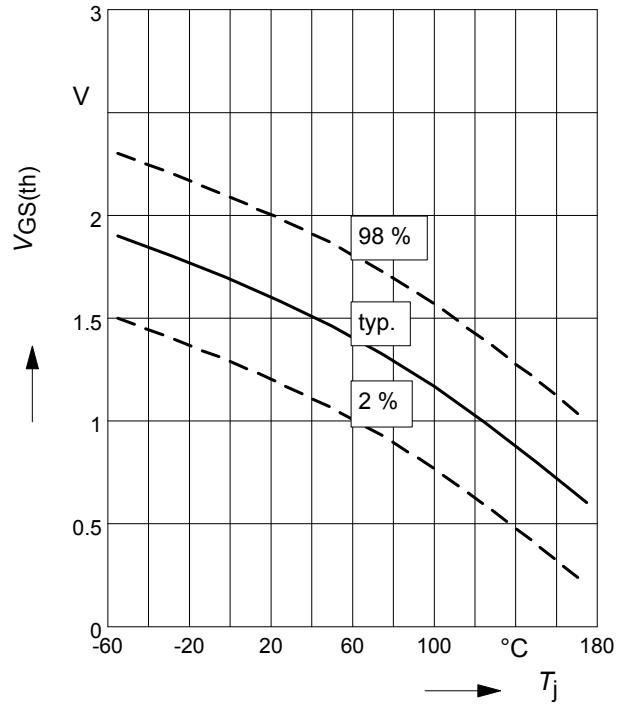
parameter :  $I_D = 30\text{ A}$ ,  $V_{GS} = 10\text{ V}$



**10 Gate threshold voltage**

$$V_{GS(th)} = f(T_j)$$

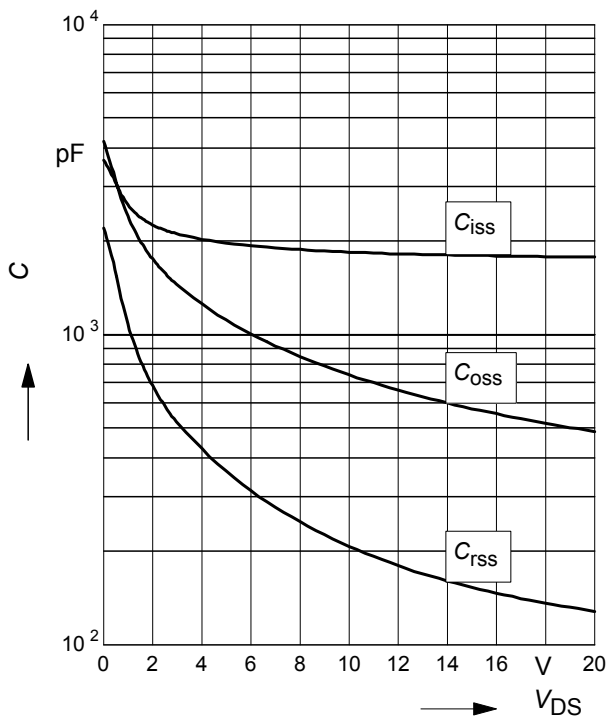
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 80\ \mu\text{A}$



**11 Typ. capacitances**

$$C = f(V_{DS})$$

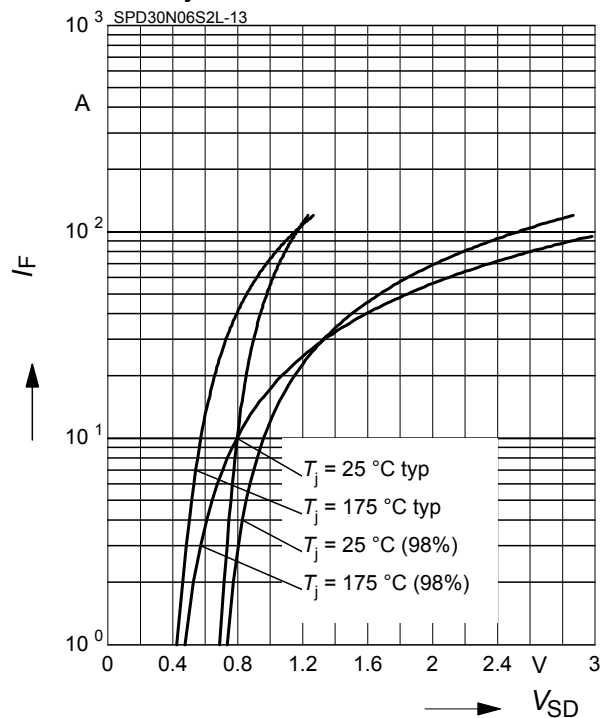
parameter:  $V_{GS}=0\text{V}$ ,  $f=1\text{ MHz}$



**12 Forward character. of reverse diode**

$$I_F = f(V_{SD})$$

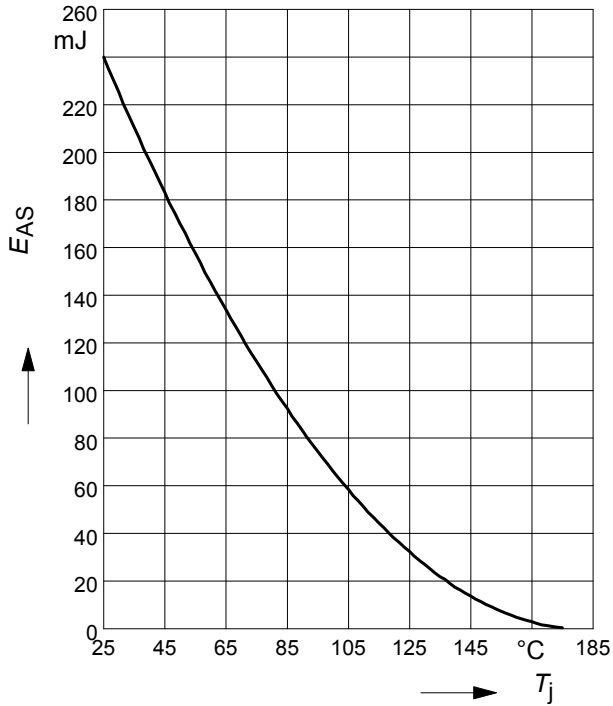
parameter:  $T_j$ ,  $t_p = 80\ \mu\text{s}$



**13 Typ. avalanche energy**

$$E_{AS} = f(T_j)$$

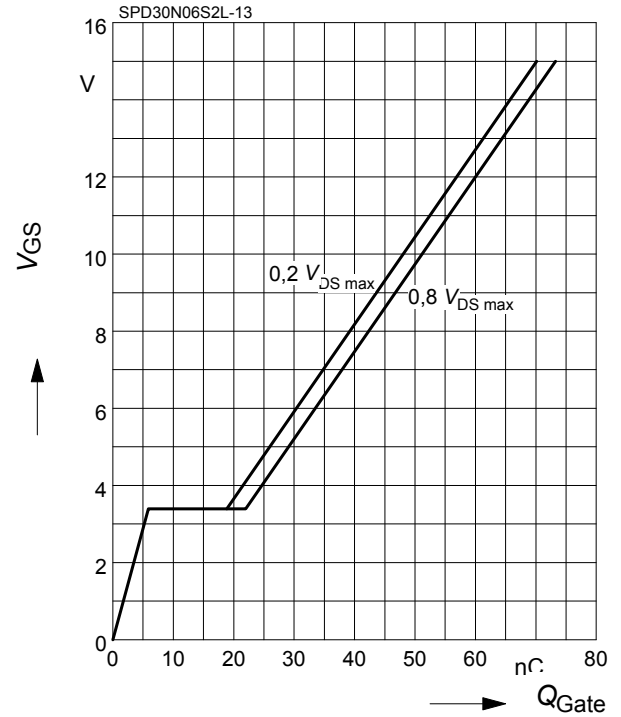
par.:  $I_D = 30\text{ A}$  ,  $V_{DD} = 25\text{ V}$  ,  $R_{GS} = 25\ \Omega$



**14 Typ. gate charge**

$$V_{GS} = f(Q_{Gate})$$

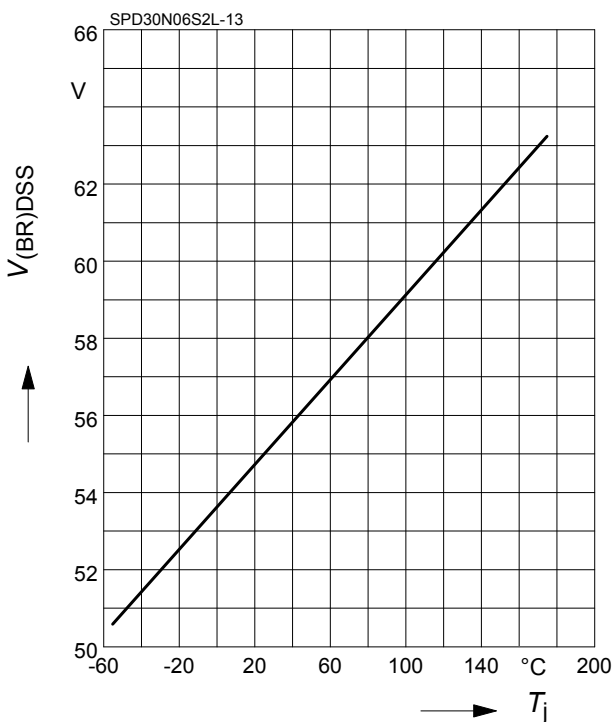
parameter:  $I_D = 30\text{ A}$  pulsed



**15 Drain-source breakdown voltage**

$$V_{(BR)DSS} = f(T_j)$$

parameter:  $I_D = 10\text{ mA}$



**Published by**  
**Infineon Technologies AG,**  
**Bereichs Kommunikation**  
**St.-Martin-Strasse 53,**  
**D-81541 München**  
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**Further information**

Please notice that the part number is BSPD30N06S2L-13, for simplicity the device is referred to by the term SPD30N06S2L-13 throughout this documentation.